



## Material Content Data Sheet



<b>Sales Product Name</b>		BSP613P H6327		<b>Issued</b>		27. September 2017		
<b>MA#</b>		MA001071052						
<b>Package</b>		PG-SOT223-4-21		<b>Weight*</b>		113.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.043	0.04		377	
	noble metal	gold	7440-57-5	0.167	0.15		1464	
	inorganic material	silicon	7440-21-3	1.890	1.66	1.85	16586	18427
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		445	
	non noble metal	chromium	7440-47-3	0.152	0.13		1335	
	non noble metal	copper	7440-50-8	50.489	44.31	44.49	443044	444913
wire	non noble metal	copper	7440-50-8	0.096	0.08	0.08	844	844
encapsulation	organic material	carbon black	1333-86-4	0.591	0.52		5185	
	plastics	epoxy resin	-	8.863	7.78		77770	
	inorganic material	silicondioxide	60676-86-0	49.631	43.55	51.85	435512	518467
leadfinish	non noble metal	tin	7440-31-5	1.464	1.28	1.28	12847	12847
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4502	4502
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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